

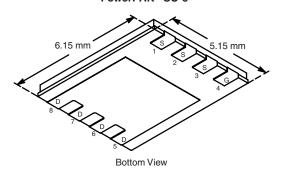


Vishay Siliconix

N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^{a, g}	Q _g (Typ.)		
30	0.0075 at V _{GS} = 10 V	30 ^g	9.5 nC		
30	0.0095 at $V_{GS} = 4.5 \text{ V}$	30 ^g	9.5110		

PowerPAK® SO-8



Ordering Information: SIR428DP-T1-GE3 (Lead (Pb)-free and Halogen-free)

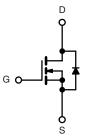
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC

ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- · Synchronous Rectification
- VRM
- Server



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unle	ss otherwise no	ted		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V_{DS}	30	V	
Gate-Source Voltage	V _{GS}	± 20			
	T _C = 25 °C		30 ^g		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	I _D	30 ^g		
Continuous Brain Current (1) = 100 °C)	T _A = 25 °C	'Б	17.4 ^{b, c}		
	T _A = 70 °C		13.8 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	60		
Continuous Source-Drain Diode Current	T _C = 25 °C	I _S	30 ^g		
Continuous Cource Diam Blode Current	T _A = 25 °C	'5	3.7 ^{b, c}		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	20		
Single Pulse Avalanche Energy			20	mJ	
	$T_C = 25 ^{\circ}C$		22.7		
Maximum Power Dissipation	$T_C = 70 ^{\circ}C$	P _D	14.5	w	
Waximum Tower Dissipation	T _A = 25 °C	. п	4.1 ^{b, c}		
	T _A = 70 °C		2.6 ^{b, c}		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	- °C		
Soldering Recommendations (Peak Temperature) ^{d, e}			260		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, f}	t ≤ 10 s	R _{thJA}	22	30	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	4.5	5.5]	

Notes:

- a. Based on T_C = 25 °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. See Solder Profile (www.vishay.com/ppg?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under Steady State conditions is 70 °C/W.
- g. Package limited.

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SPECIFICATIONS $T_J = 25 ^{\circ}C$, Parameter	1	Test Conditions	Min.	Tren	Max.	Unit
Static	Symbol	rest Conditions	IVIIII.	Тур.	IVIAX.	Ollit
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30	1	<u> </u>	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	· GS		27		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \mu A$		- 4.4		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1.2	7.7	2.5	V
Gate-Source Leakage		$V_{DS} = 0 \text{ V, } V_{GS} = \pm 20 \text{ V}$	1.2		± 100	nA
Gate-Source Leakage	I _{GSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 20 \text{ V}$			1	ш
Zero Gate Voltage Drain Current		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			10	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α
Drain-Source On-State Resistance ^a	Б	$V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$		0.0061	0.0075	
	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$		0.0077	0.0095	Ω
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 10 \text{ V}, I_{D} = 10 \text{ A}$		46		S
Dynamic ^b	<u>'</u>			•	•	L
Input Capacitance	C _{iss}			1117		pF
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		274		
Reverse Transfer Capacitance	C _{rss}			80		
Total Gate Charge	Q_g	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$		21	32	nC
	_			9.5	14.5	
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		2.8		
Gate-Drain Charge	Q _{gd}			2.8		
Gate Resistance	R_g	f = 1 MHz	0.2	0.5	1.0	Ω
Turn-On Delay Time	t _{d(on)}			8	16	
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_L = 1.5 \Omega$		10	20	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		17	34	
Fall Time	t _f			8	16	ns
Turn-On Delay Time	t _{d(on)}			16	32	113
Rise Time	t _r	V_{DD} = 10 V, R_L = 1 Ω		11	22	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		18	36	
Fall Time	t _f			9	18	
Drain-Source Body Diode Characteristic	cs					
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			30	Α
Pulse Diode Forward Current ^a	I _{SM}				60	
Body Diode Voltage	V_{SD}	I _S = 3 A		0.75	1.1	V
Body Diode Reverse Recovery Time	t _{rr}			22	40	ns
Body Diode Reverse Recovery Charge	Q _{rr}	L = 10 A dl/dt = 100 A/vo T = 05 °C		15.5	28	nC
Reverse Recovery Fall Time	t _a	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		14		
Reverse Recovery Rise Time	t _b			8	1	ns

Notes:

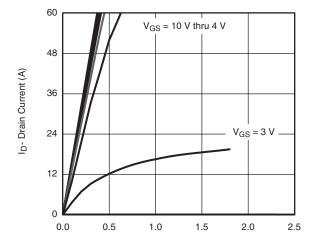
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



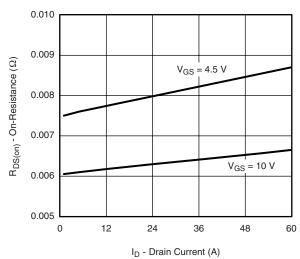
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

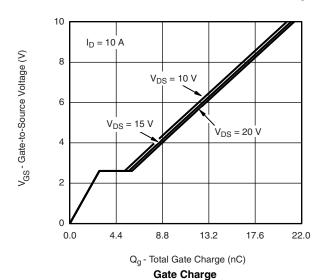


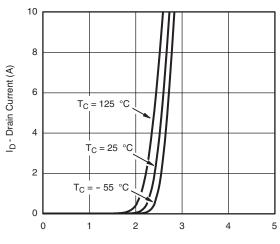
 V_{DS} - Drain-to-Source Voltage (V)

Output Characteristics

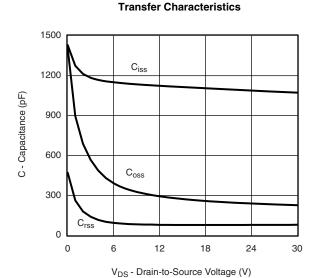


On-Resistance vs. Drain Current and Gate Voltage

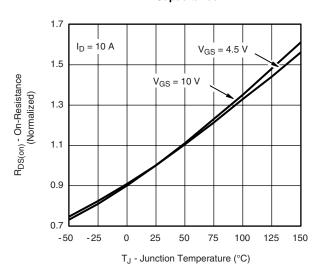




V_{GS} - Gate-to-Source Voltage (V)



Capacitance



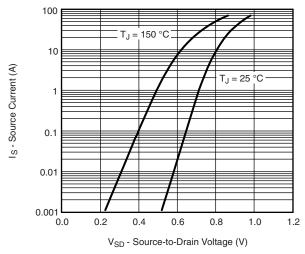
On-Resistance vs. Junction Temperature

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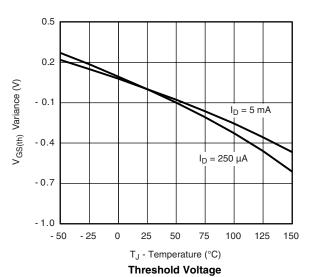
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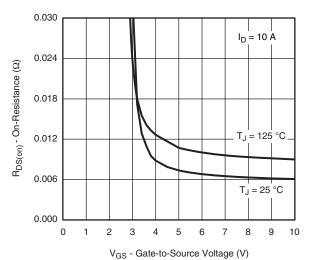
VISHAY.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

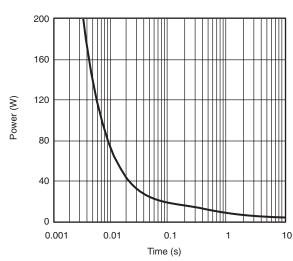


Source-Drain Diode Forward Voltage

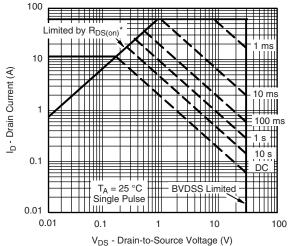




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



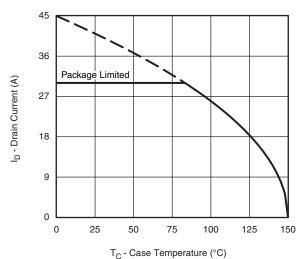
* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

Safe Operating Area, Junction-to-Ambient

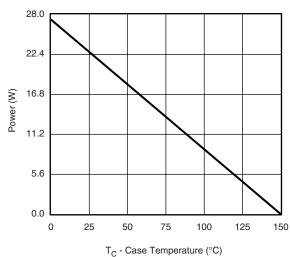


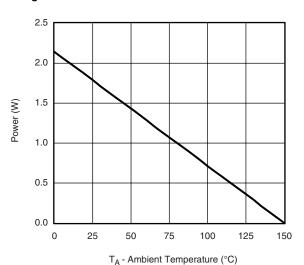
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*





Power, Junction-to-Case

Power, Junction-to-Ambient

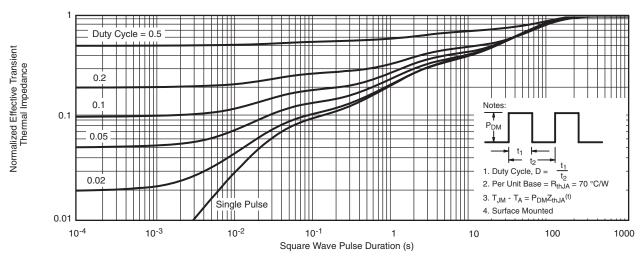
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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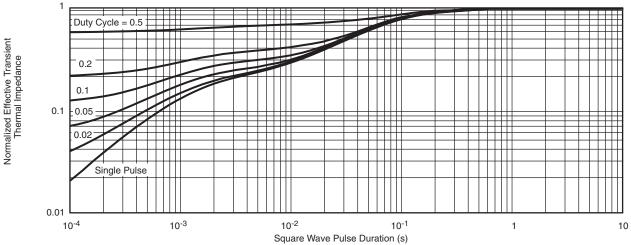
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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